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(12) United States Design Patent
Buck et al.

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(45) **Date of Patent: ** Mar. 31, 2020**

(54) **CONTACT WAFER**

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(73) Assignee: **SAMTEC, INC.**, New Albany, IN (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/647,260**

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Related U.S. Application Data

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/154**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 154, 184, 199
CPC .. H01R 4/2404; H01R 4/2425; H01R 4/2462; H01R 4/26; H01R 9/09; H01R 9/091; H01R 9/16; H01R 9/22; H01R 9/226; H01R 12/50; H01R 12/51; H01R 12/52; H01R 12/57; H01R 12/58; H01R 12/59; H01R 12/592; H01R 12/62; H01R 12/70; H01R 12/7005; H01R 12/73; H01R 12/732; H01R 12/737; H01R 12/777; H01R 12/778; H01R 12/79; H01R 13/05
See application file for complete search history.

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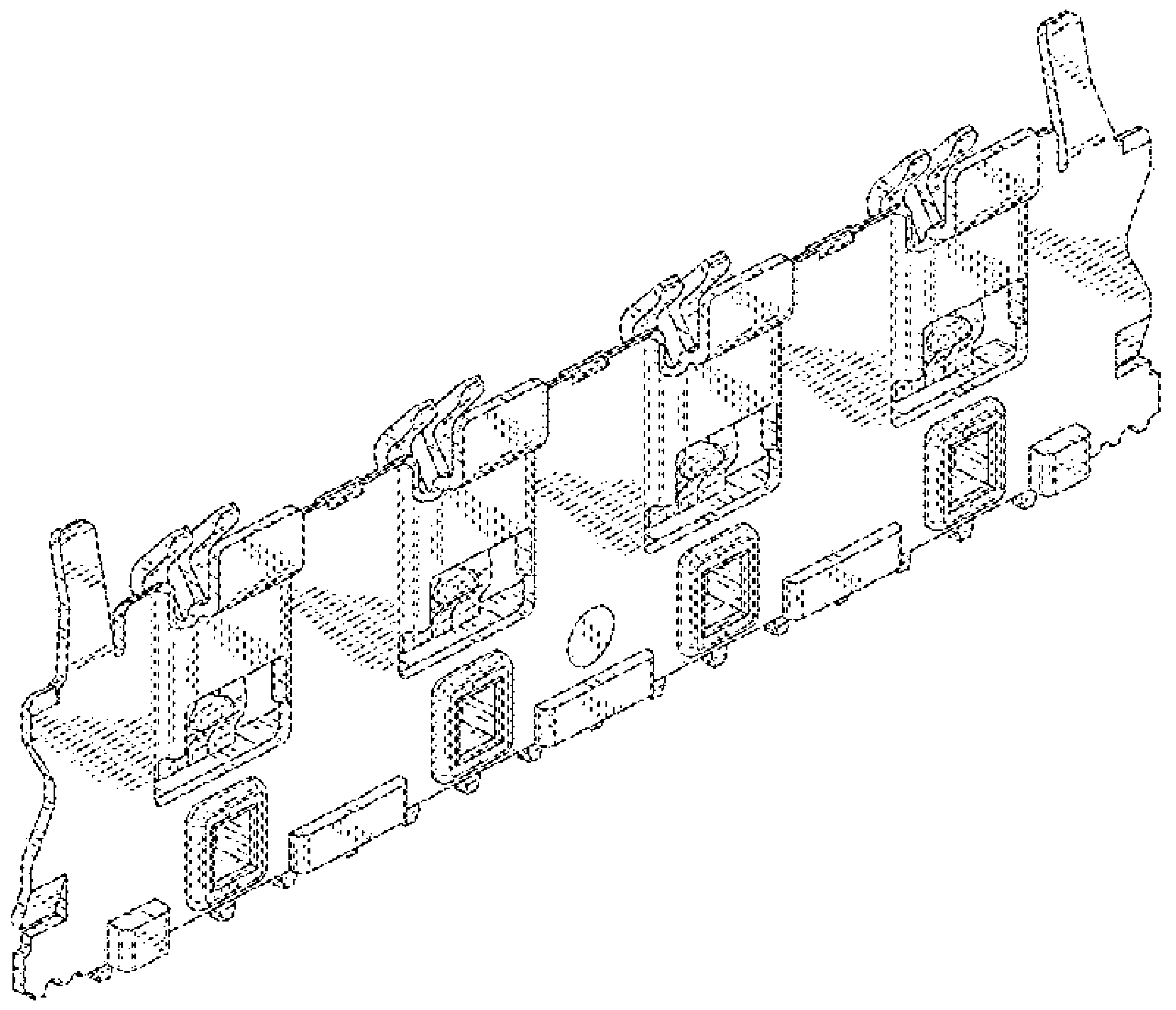
(57) CLAIM

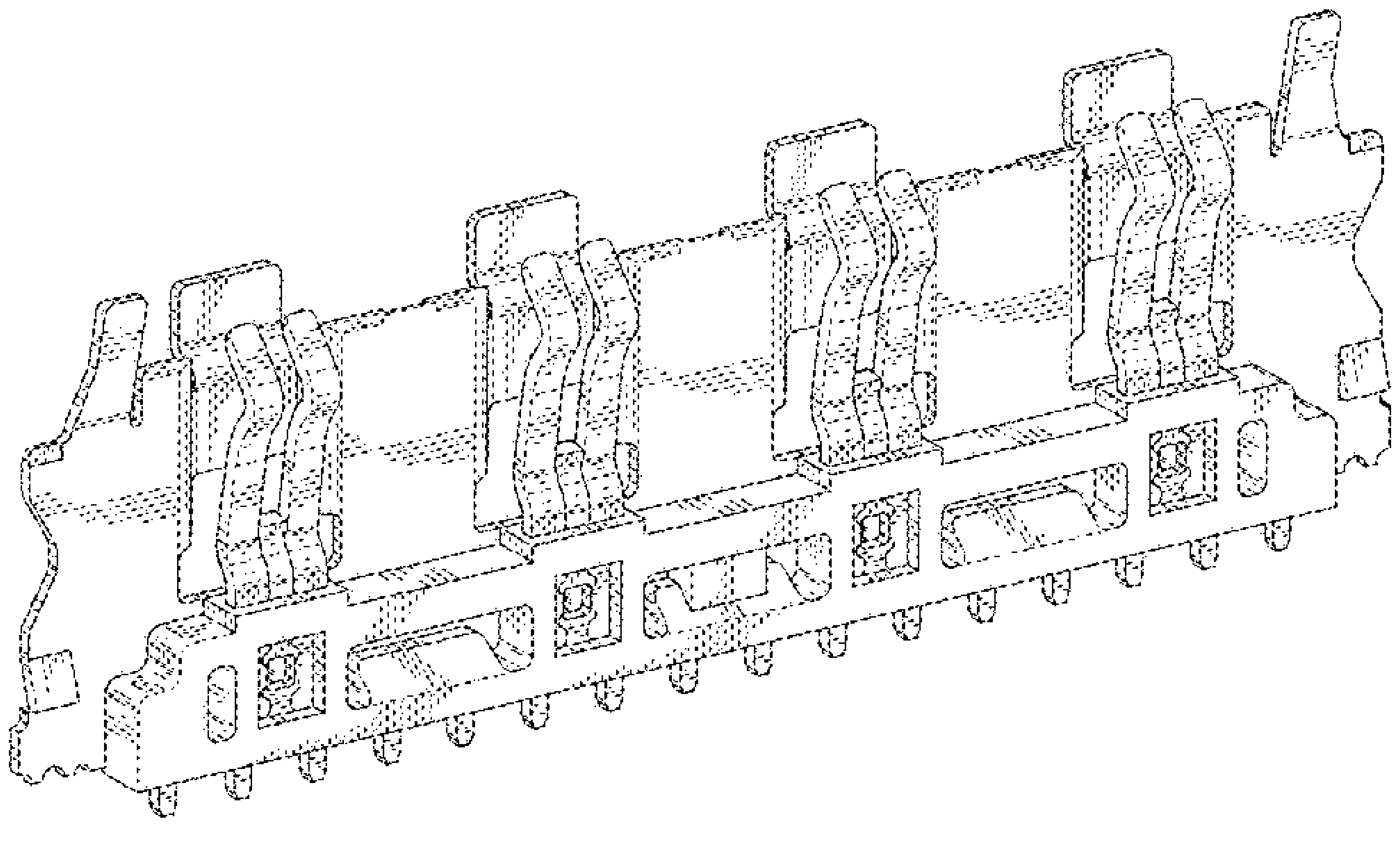
The ornamental design for a contact wafer, as shown and described.

DESCRIPTION

FIG. **1** is a top, front, and right side perspective view of a contact wafer showing our new design;
FIG. **2** is a top, back, and left side perspective view thereof;
FIG. **3** is a left side elevation view thereof;
FIG. **4** is a right side elevation view thereof;
FIG. **5** is a front elevation view thereof;
FIG. **6** is a back elevation view thereof;
FIG. **7** is a top plan view thereof; and,
FIG. **8** is a bottom plan view thereof.

1 Claim, 6 Drawing Sheets





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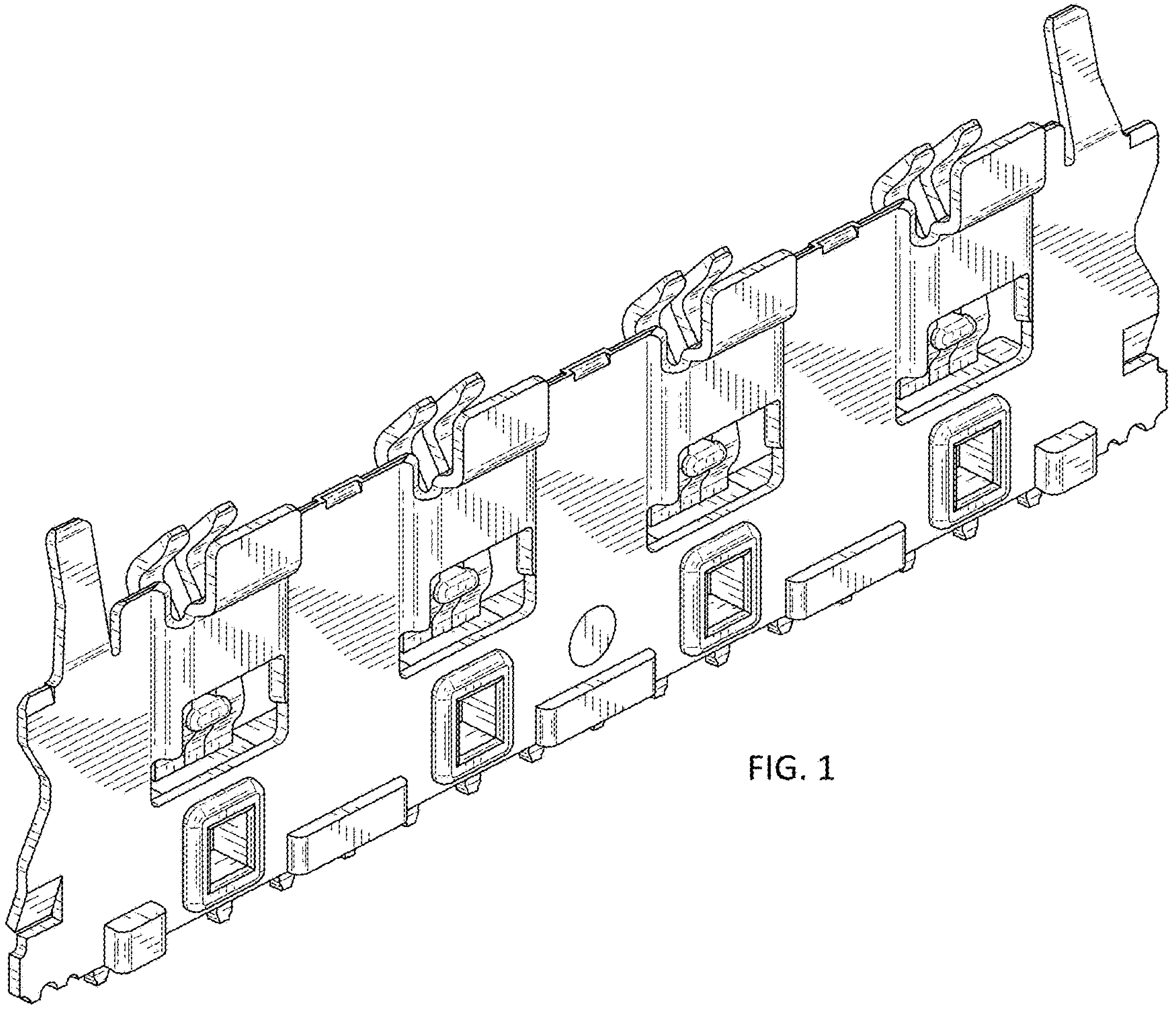

FIG. 1

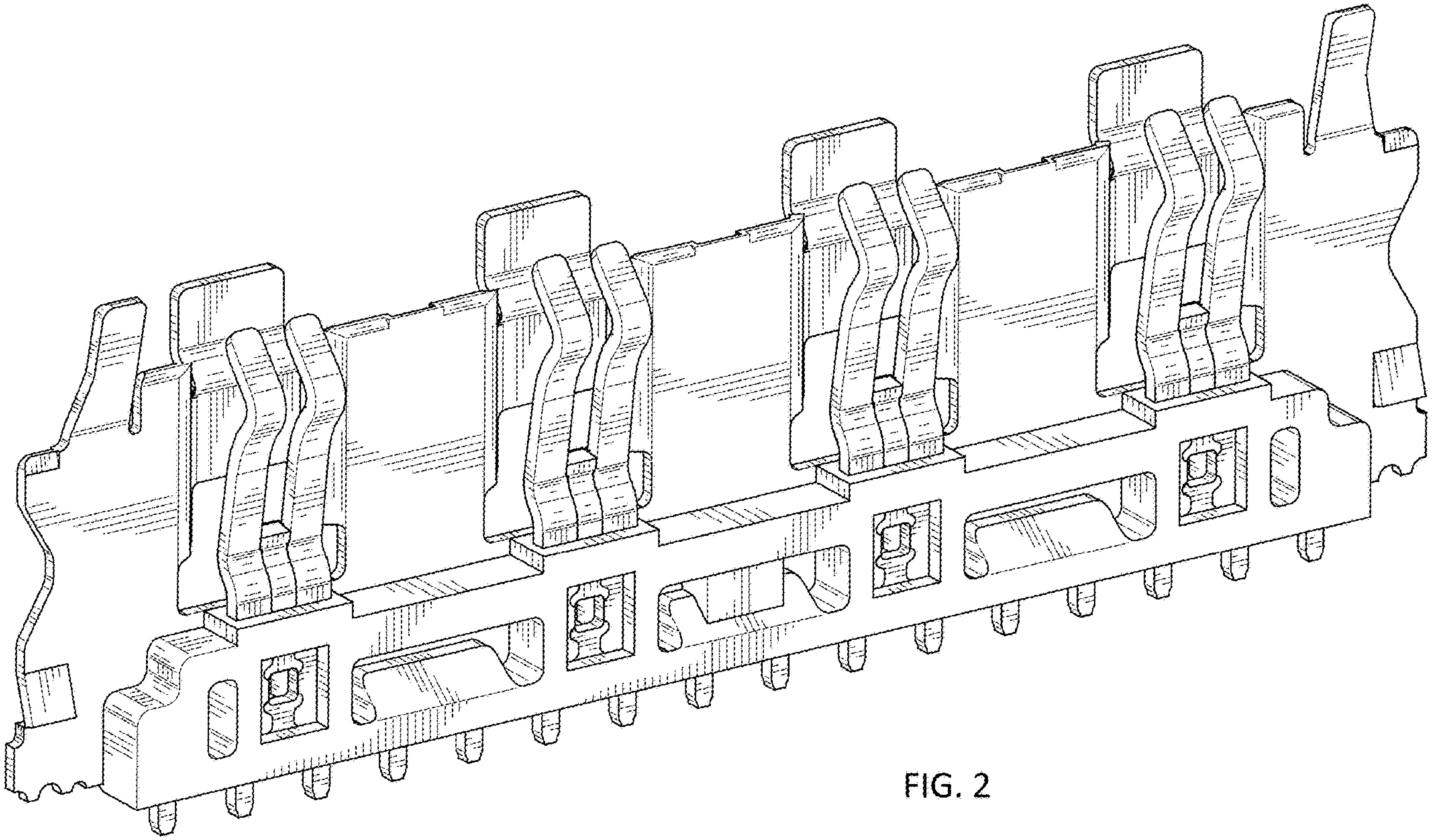

FIG. 2

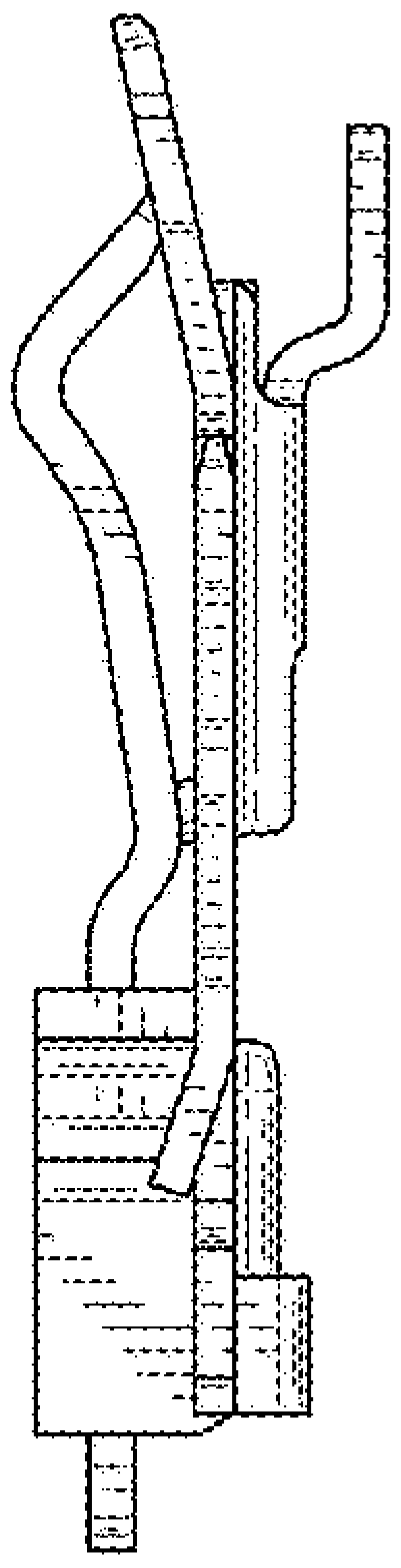

FIG. 3

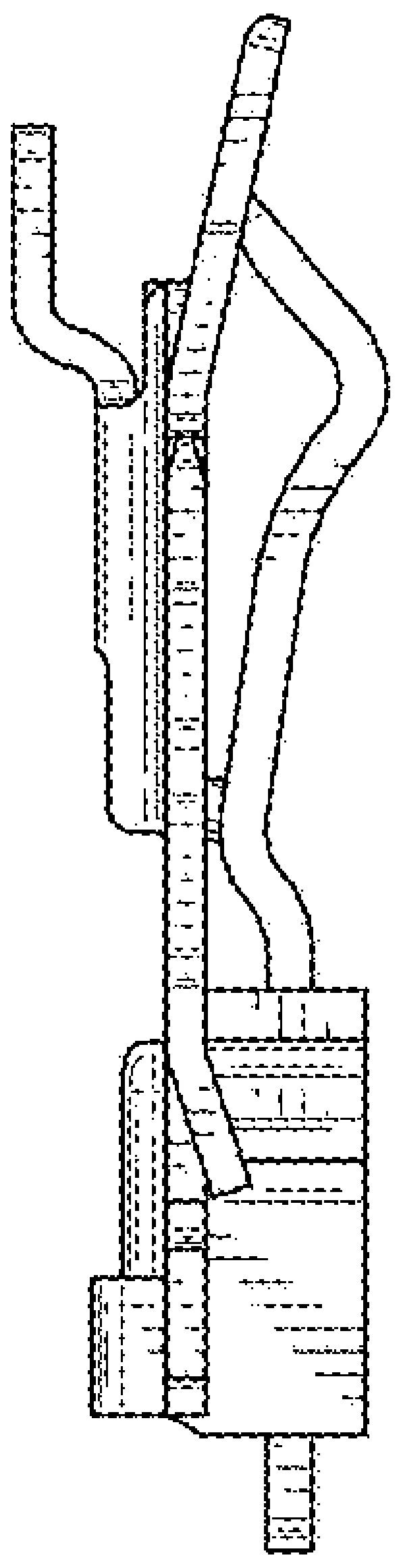

FIG. 4

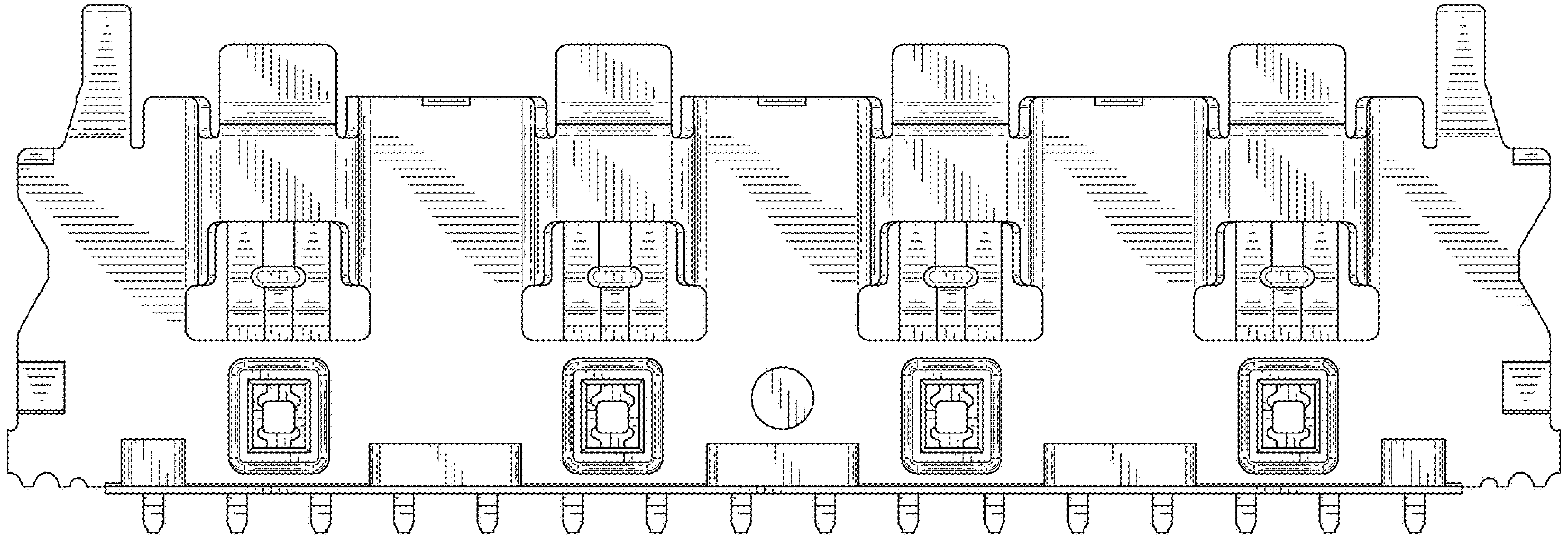

FIG. 5

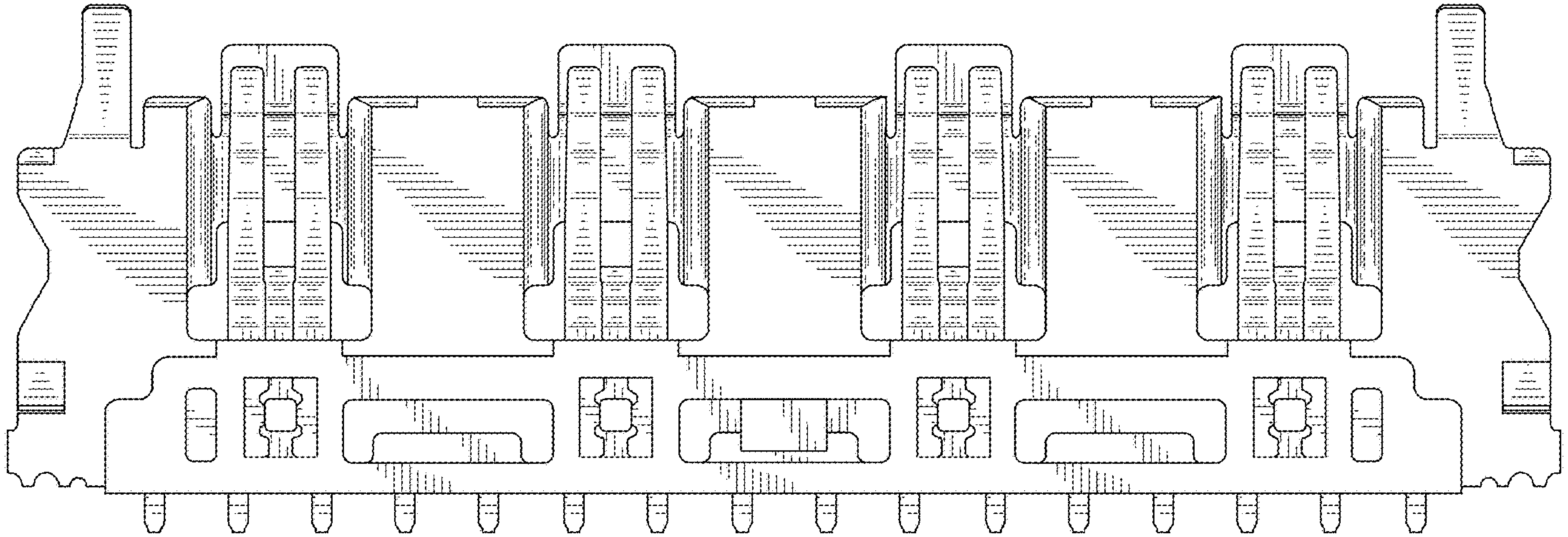

FIG. 6

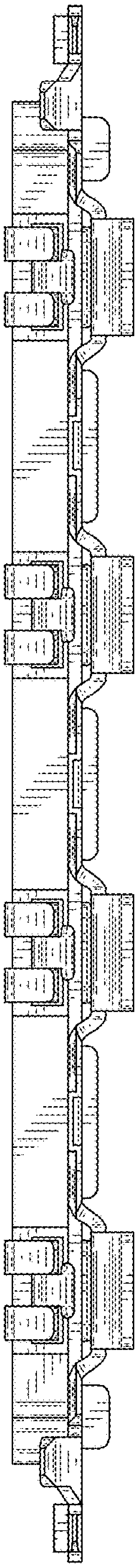

FIG. 7

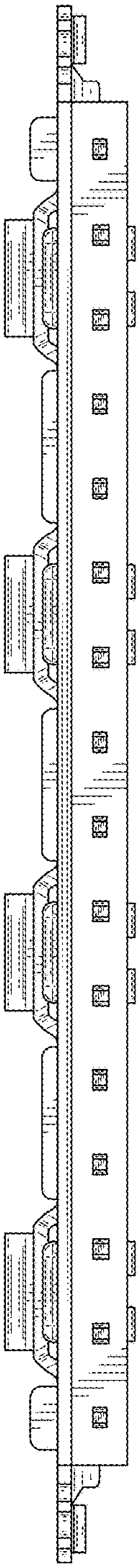

FIG. 8